

CALL FOR PAPERS



深圳产学研合作促进会
Shenzhen Industry-University-Research
Institute Collaboration Association



IEEE-EPIC 2026

The 2026 1st IEEE International Conference on Advanced
Sensing for Embodied Perception and PhysICal AI
先进传感赋能具身感知与物理人工智能国际会议

4-7 December, 2026

Shenzhen, China (中国·深圳)

Jen Shenzhen Qianhai by Shangri-La



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Topic of Interests

- ✓ Novel Sensing Modalities and Transducers
- ✓ Sensor Materials, Fabrication and Packaging Technologies
- ✓ Wearable, Implantable & Epidermal Sensors
- ✓ Energy Harvesting & Self-Powered Sensing
- ✓ Edge Sensing & Embedded/Low-Power Technologies
- ✓ AI Sensor Interfaces & Readout Circuits
- ✓ LiDAR, Millimeter Wave, Ultrasonic & Acoustic Sensing
- ✓ Digital Twin & Simulation Technologies
- ✓ Robotic Tactile, Force/Torque & Proprioceptive Sensing
- ✓ Multimodal Sensing and Sensor Fusion
- ✓ Embodied Intelligent Perception (SLAM, Tracking)
- ✓ Perception-Action Learning and Closed-Loop Control
- ✓ Robot Demonstration Learning & HRI
- ✓ Human-Robot Interaction & Intent Recognition
- ✓ Healthcare & Assistive Applications
- ✓ Privacy Protection & Trustworthy Sensing

Important Dates

- Paper Submission
Aug 01 - Aug 31, 2026
- Paper Review
Sep 01 - Sep 20, 2026
- Notification of Acceptance
Sep 30, 2026
- Full Paper Submission
Oct 30, 2026
- Conference
Dec 04 - 07, 2026



Useful Links

Conference Website

<https://www.ieee-epic.org/>

Paper Submission

https://www.ieee-epic.org/?page_id=759

Hotel Website

<https://www.shangri-la.com/hotels/jen/shenzhen/qianhai/>



Journal Publication

Authors of Accepted Full Papers will be invited to submit their work for publication in a Special Issue of the IEEE Open Journal of Nanotechnology.